IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A method of operating an ~~An~~ automolding system comprising:
providing a substrate having a surface in the automolding system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

2. (Currently Amended) The method of operating an automolding system of claim 1, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

3. (Currently Amended) The method of operating an automolding system of claim 1, further comprising:
placing the substrate in a mold; and
encapsulating the substrate in the automolding system.

4. (Currently Amended) A method of using a molding system comprising:
providing a substrate having a surface in the molding system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

5. (Currently Amended) The method of using a molding system of claim 4, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

6. (Currently Amended) The method of using a molding system of claim 4, further comprising:
placing the substrate in a mold in the molding system; and
encapsulating the substrate.

7. (Currently Amended) A method for operating a ~~A~~ system for molding comprising:
providing a substrate having a surface for molding in the system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

8. (Currently Amended) The method for operating a system of claim 7, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

9. (Currently Amended) The method for operating a system of claim 7, further comprising:
placing the substrate in a mold in the system; and
encapsulating the substrate.

10. (Currently Amended) A method for molding in ~~In~~ an automolding system comprising:
placing a substrate having a surface in the automolding system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

11. (Currently Amended) The method for molding in an automolding system of claim 10, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

12. (Currently Amended) The method for molding in an automolding system of claim 10, further comprising:
placing the substrate in a mold; and
encapsulating the substrate in the automolding system.

13. (Currently Amended) In a molding system a method comprising:
placing a substrate having a surface in the molding system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

14. (Currently Amended) In the ~~The~~ molding system of claim 13 the method ~~3~~, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

15. (Currently Amended) In the ~~The~~ molding system of claim 13 the method ~~3~~, further comprising:
placing the substrate in a mold in the molding system; and
encapsulating the substrate.

16. (Currently Amended) A method in ~~In~~ a system for molding comprising:
placing a substrate having a surface for molding in the system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

17. (Currently Amended) The method of the system of claim 16, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

18. (Currently Amended) The method of the system of claim 16, further comprising:
placing the substrate in a mold in the system; and
encapsulating the substrate.

19. (Currently Amended) A method for using ~~In~~ an automolding system having a cleaning apparatus comprising:
introducing a substrate having a surface in the automolding system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using a laser.

20. (Currently Amended) The method for using an automolding system of claim 19, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

21. (Currently Amended) The method for using an automolding system of claim 19, further comprising:
placing the substrate in a mold; and
encapsulating the substrate in the automolding system.

22. (Currently Amended) A method for using a molding system having a substrate cleaning device comprising:
introducing a substrate having a surface in the molding system;
preheating the substrate;
forming a resist layer;

baking the substrate; and

removing contaminants from the substrate using a laser.

23. (Currently Amended) The method for using a molding system of claim 22, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

24. (Currently Amended) The method for isomg a molding system of claim 22, further comprising:

placing the substrate in a mold in the molding system; and

encapsulating the substrate.

25. (Currently Amended) A method for operating a system having a cleaning device for molding comprising:

introducing a substrate having a surface for molding in the system;

preheating the substrate;

forming a resist layer;

baking the substrate; and

removing contaminants from the substrate using a laser.

26. (Currently Amended ) The method for operating a system of claim 15, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

27. (Currently Amended) The method for operating a system of claim 15, further comprising:

placing the substrate in a mold in the system; and

encapsulating the substrate.

28. (Currently Amended) A method for use in ~~In~~ an automolding system comprising:

providing a substrate cleaning device for the automolding system;

introducing a substrate having a surface in the automolding system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using the cleaning device.

29. (Currently Amended) The method for use in an automolding system of claim 28, wherein the substrate cleaning device comprises a laser.

30. (Currently Amended) The method for use in an automolding system of claim 29, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

31. (Currently Amended) The method for use in an automolding system of claim 28, further comprising:
placing the substrate in a mold; and
encapsulating the substrate in the automolding system.

32. (Currently Amended) A method for forming in a molding system comprising:
providing the molding system with a substrate cleaning device;
introducing a substrate having a surface in the molding system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using the substrate cleaning ~~devicer~~ device.

33. (Currently Amended) The method for forming in a molding system of claim 32, wherein the substrate cleaning device comprises a laser.

34. (Currently Amended) The method for forming in a molding system of claim 33, wherein the substrate cleaning device comprises a laser.

35. (Currently Amended) The method for forming in a molding system of claim 32, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

36. (Currently Amended) The method for forming in a molding system of claim 32, further comprising:
placing the substrate in a mold in the molding system; and
encapsulating the substrate.

37. (Currently Amended) A method for a system for molding comprising:
providing a substrate cleaning device in the system for molding;
introducing a substrate having a surface for molding in the system;
preheating the substrate;
forming a resist layer;
baking the substrate; and
removing contaminants from the substrate using the substrate cleaning device.

38. (Currently Amended) The method for a system of claim 37, wherein the substrate cleaning device comprises a laser.

39. (Currently Amended) The method for a system of claim 38, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

40. (Currently Amended) The method for a system of claim 37, further comprising:
placing the substrate in a mold in the system; and
encapsulating the substrate.